

Recommended reflow temperature profile using lead-free solder paste. ◆ Recommended PCB layout MAX 250 ℃ 3.47 ± 0.02 1.7 ± 0.02 220 °C (0.83) 0.4 ± 0.02 180 °C \bigcirc EMPERATURE 150 °C DRAMING FOR PEREN 0.23 ± 0.02 90∼120 sec. MAX 60 sec. PRE-HEATING TIME SOLDERING TIME Recommended metal mask dimensions TIME (sec.) Metal mask thickness: 100 4 m Reflow method: IR reflow Number of reflow cycles: 2 cycles MAX. 1)Reflow time Duration above 220°C, 60 sec MAX. (Peak temperature:250℃ MAX) ≥>Pre-heat time 3.47 ± 0.02 Pre-heat temperature(MIN):150℃ Pre-heat temperature(MAX):180℃ 1.7 ± 0.02 (0.83) re-heut time:90-120 sec. 0.4 ± 0.02 The temperatures mentioned above refer to the PCB surface temperature near the connector leads. The temperature profiles are based on the above conditions. In individual applications the actual temperature may vary, 0.38 ± 0.01 depending on solder paste type.volume/thickness and board size/thickness. Consult your solder paste and equipment manufacturer for specific 1.74 ± 0.07 0.23 ± 0.01

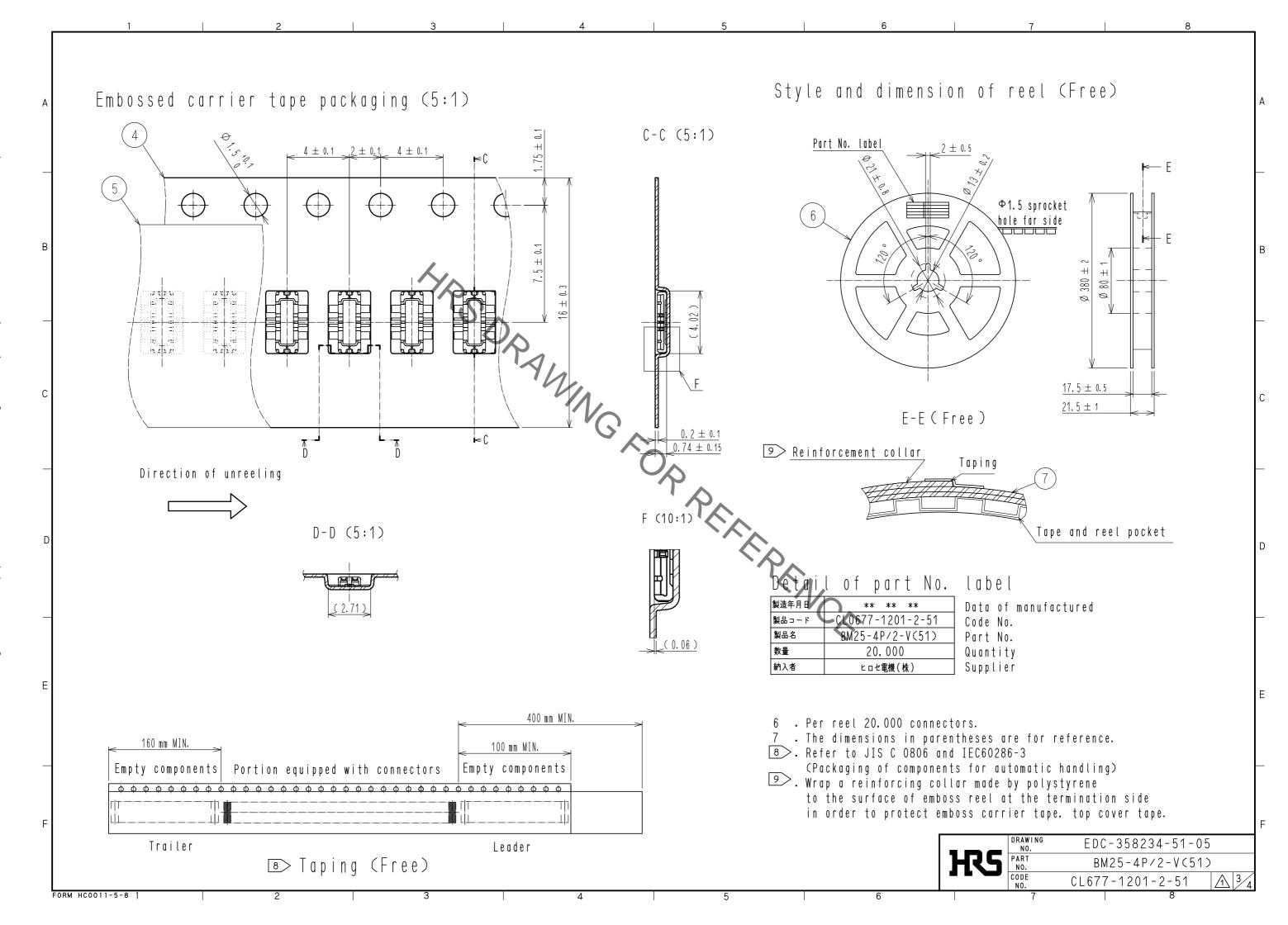
> EDC-358234-51-05 HRS PART NO. BM25-4P/2-V(51) CL677-1201-2-51

5. Please contact us in case you will make different settings

from our recommendation.

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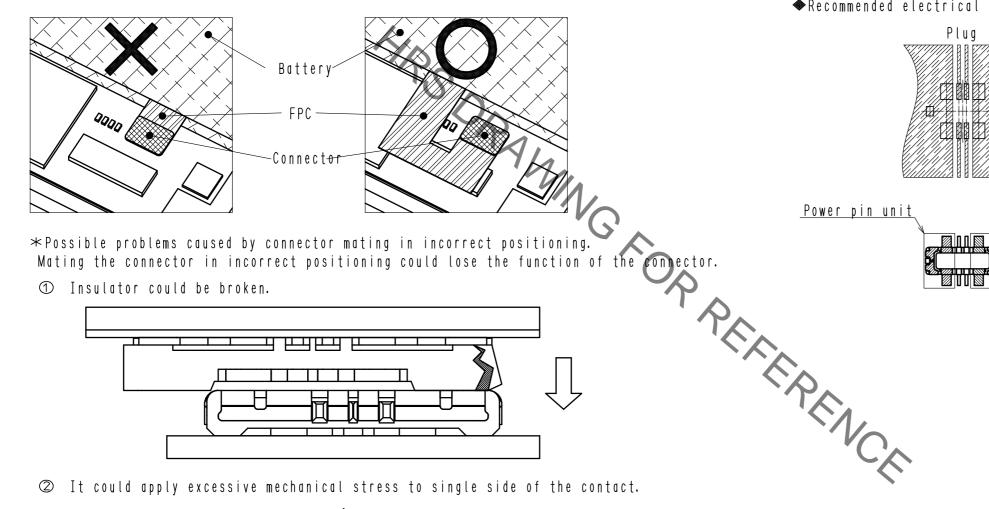
 0.64 ± 0.01

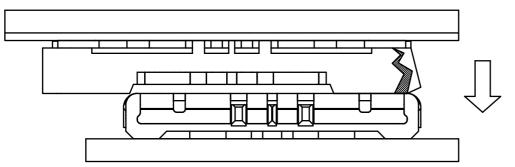


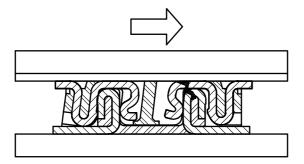
■ How to draw the FPC

BM25 series connector is intended to carry 10A electrical current for battery application. FPC may have less flexibility than usual, since the copper foil becomes wider and thicker to carry

Please design the FPC to have a flexibility to absorb the displacement* of the connector cased by fixing PCB and battery.



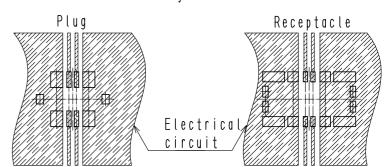




■ How to draw the electrical circuit

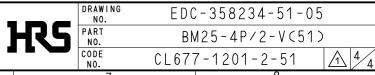
As shown in the figure below, each power supply unit including the lock metal fitting has to be mounted on the same PCB circuit.

◆Recommended electrical circuit layout



Power pin unit Power pin unit

② It could apply excessive mechanical stress to single side of the contact.



Power pin unit

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